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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	640
Number of Logic Elements/Cells	6400
Total RAM Bits	81920
Number of I/O	271
Number of Gates	404000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	356-LBGA
Supplier Device Package	356-BGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k160ebc356-1aa

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

General Description

APEXTM 20K devices are the first PLDs designed with the MultiCore architecture, which combines the strengths of LUT-based and product-term-based devices with an enhanced memory structure. LUT-based logic provides optimized performance and efficiency for data-path, register-intensive, mathematical, or digital signal processing (DSP) designs. Product-term-based logic is optimized for complex combinatorial paths, such as complex state machines. LUT- and product-term-based logic combined with memory functions and a wide variety of MegaCore and AMPP functions make the APEX 20K device architecture uniquely suited for system-on-a-programmable-chip designs. Applications historically requiring a combination of LUT-, product-term-, and memory-based devices can now be integrated into one APEX 20K device.

APEX 20KE devices are a superset of APEX 20K devices and include additional features such as advanced I/O standard support, CAM, additional global clocks, and enhanced ClockLock clock circuitry. In addition, APEX 20KE devices extend the APEX 20K family to 1.5 million gates. APEX 20KE devices are denoted with an "E" suffix in the device name (e.g., the EP20K1000E device is an APEX 20KE device). Table 8 compares the features included in APEX 20K and APEX 20KE devices.

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

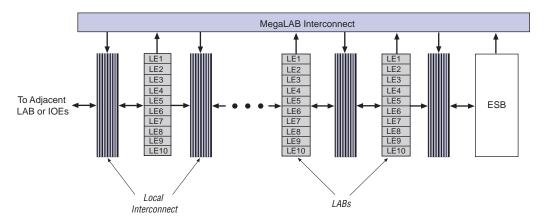
The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

APEX 20K devices provide two dedicated clock pins and four dedicated input pins that drive register control inputs. These signals ensure efficient distribution of high-speed, low-skew control signals. These signals use dedicated routing channels to provide short delays and low skews. Four of the dedicated inputs drive four global signals. These four global signals can also be driven by internal logic, providing an ideal solution for a clock divider or internally generated asynchronous clear signals with high fan-out. The dedicated clock pins featured on the APEX 20K devices can also feed logic. The devices also feature ClockLock and ClockBoost clock management circuitry. APEX 20KE devices provide two additional dedicated clock pins, for a total of four dedicated clock pins.

MegaLAB Structure

APEX 20K devices are constructed from a series of MegaLABTM structures. Each MegaLAB structure contains a group of logic array blocks (LABs), one ESB, and a MegaLAB interconnect, which routes signals within the MegaLAB structure. The EP20K30E device has 10 LABs, EP20K60E through EP20K600E devices have 16 LABs, and the EP20K1000E and EP20K1500E devices have 24 LABs. Signals are routed between MegaLAB structures and I/O pins via the FastTrack Interconnect. In addition, edge LABs can be driven by I/O pins through the local interconnect. Figure 2 shows the MegaLAB structure.

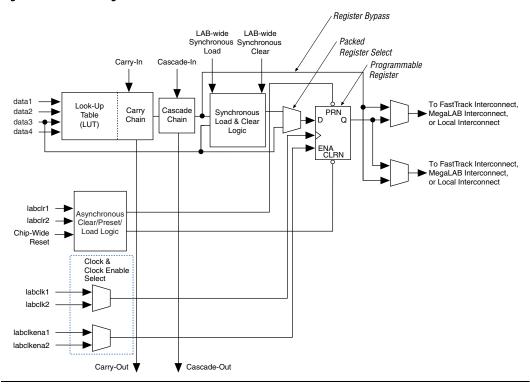
Figure 2. MegaLAB Structure



Logic Element

The LE, the smallest unit of logic in the APEX 20K architecture, is compact and provides efficient logic usage. Each LE contains a four-input LUT, which is a function generator that can quickly implement any function of four variables. In addition, each LE contains a programmable register and carry and cascade chains. Each LE drives the local interconnect, MegaLAB interconnect, and FastTrack Interconnect routing structures. See Figure 5.

Figure 5. APEX 20K Logic Element



Each LE's programmable register can be configured for D, T, JK, or SR operation. The register's clock and clear control signals can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinatorial functions, the register is bypassed and the output of the LUT drives the outputs of the LE.

Input/Output Clock Mode

The input/output clock mode contains two clocks. One clock controls all registers for inputs into the ESB: data input, WE, RE, read address, and write address. The other clock controls the ESB data output registers. The ESB also supports clock enable and asynchronous clear signals; these signals also control the reading and writing of registers independently. Input/output clock mode is commonly used for applications where the reads and writes occur at the same system frequency, but require different clock enable signals for the input and output registers. Figure 21 shows the ESB in input/output clock mode.

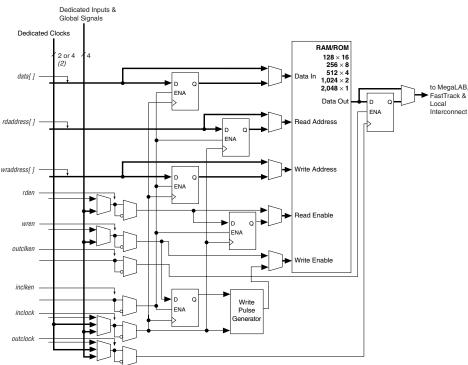


Figure 21. ESB in Input/Output Clock Mode Note (1)

Notes to Figure 21:

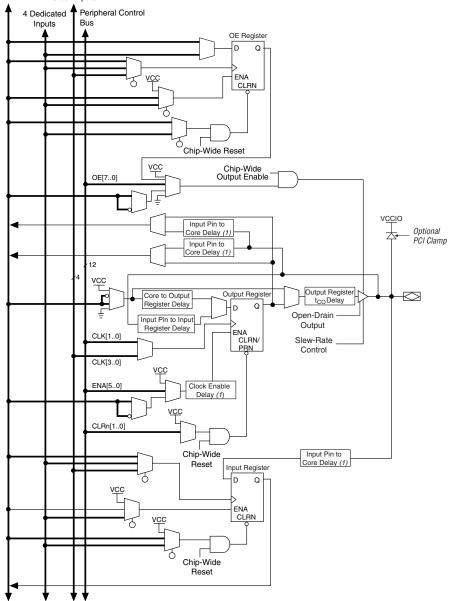
- (1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

Single-Port Mode

The APEX 20K ESB also supports a single-port mode, which is used when simultaneous reads and writes are not required. See Figure 22.

Figure 26. APEX 20KE Bidirectional I/O Registers Notes (1), (2)

Row, Column, FastRow, 4 Dedicated or Local Interconnect Clock Inputs

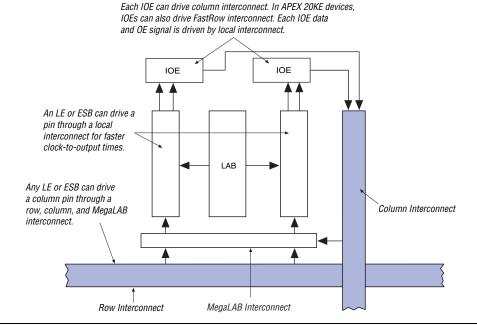


Notes to Figure 26:

- (1) This programmable delay has four settings: off and three levels of delay.
- (2) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Figure 28 shows how a column IOE connects to the interconnect.

Figure 28. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KE devices incorporate an enhancement to support bidirectional pins with high internal fanout such as PCI control signals. These pins are called Dedicated Fast I/O pins (FAST1, FAST2, FAST3, and FAST4) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fanout logic signal distribution. They also can drive out. The Dedicated Fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Advanced I/O Standard Support

APEX 20KE IOEs support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KE devices, see *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

The APEX 20KE device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a particular bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K300E and larger APEX 20KE devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K300E and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400E devices and larger with an X-suffix on the ordering code add a serializer/deserializer circuit and PLL for higher-speed support.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used as LVDS I/O banks, they support all of the other I/O standards. Figure 29 shows the arrangement of the APEX 20KE I/O banks.

For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to CLK2p. Table 14 shows the combinations supported by the ClockLock and ClockBoost circuitry. The CLK2p pin can feed both the ClockLock and ClockBoost circuitry in the APEX 20K device. However, when both circuits are used, the other clock pin (CLK1p) cannot be used.

Table 14. Multiplication Factor Combinations					
Clock 1 Clock 2					
×1	×1				
×1,×2	×2				
×1, ×2, ×4	×4				

APEX 20KE ClockLock Feature

APEX 20KE devices include an enhanced ClockLock feature set. These devices include up to four PLLs, which can be used independently. Two PLLs are designed for either general-purpose use or LVDS use (on devices that support LVDS I/O pins). The remaining two PLLs are designed for general-purpose use. The EP20K200E and smaller devices have two PLLs; the EP20K300E and larger devices have four PLLs.

The following sections describe some of the features offered by the APEX 20KE PLLs.

External PLL Feedback

The ClockLock circuit's output can be driven off-chip to clock other devices in the system; further, the feedback loop of the PLL can be routed off-chip. This feature allows the designer to exercise fine control over the I/O interface between the APEX 20KE device and another high-speed device, such as SDRAM.

Clock Multiplication

The APEX 20KE ClockBoost circuit can multiply or divide clocks by a programmable number. The clock can be multiplied by $m/(n \times k)$ or $m/(n \times v)$, where m and k range from 2 to 160, and n and v range from 1 to 16. Clock multiplication and division can be used for time-domain multiplexing and other functions, which can reduce design LE requirements.

Clock Phase & Delay Adjustment

The APEX 20KE ClockShift feature allows the clock phase and delay to be adjusted. The clock phase can be adjusted by 90° steps. The clock delay can be adjusted to increase or decrease the clock delay by an arbitrary amount, up to one clock period.

LVDS Support

Two PLLs are designed to support the LVDS interface. When using LVDS, the I/O clock runs at a slower rate than the data transfer rate. Thus, PLLs are used to multiply the I/O clock internally to capture the LVDS data. For example, an I/O clock may run at 105 MHz to support 840 megabits per second (Mbps) LVDS data transfer. In this example, the PLL multiplies the incoming clock by eight to support the high-speed data transfer. You can use PLLs in EP20K400E and larger devices for high-speed LVDS interfacing.

Lock Signals

The APEX 20KE ClockLock circuitry supports individual LOCK signals. The LOCK signal drives high when the ClockLock circuit has locked onto the input clock. The LOCK signals are optional for each ClockLock circuit; when not used, they are I/O pins.

ClockLock & ClockBoost Timing Parameters

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the APEX 20K ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. In APEX 20KE devices, the clock input standard is programmable, so the PLL cannot respond to the clock until the device is configured. The PLL locks onto the input clock as soon as configuration is complete. Figure 30 shows the incoming and generated clock specifications.



For more information on ClockLock and ClockBoost circuitry, see *Application Note 115: Using the ClockLock and ClockBoost PLL Features in APEX Devices*.

Table 15. APEX 20K ClockLock & ClockBoost Parameters for -1 Speed-Grade Devices (Part 2 of 2)							
Symbol	Parameter	Min	Max	Unit			
t _{SKEW}	Skew delay between related ClockLock/ClockBoost-generated clocks		500	ps			
t _{JITTER}	Jitter on ClockLock/ClockBoost-generated clock (5)		200	ps			
t _{INCLKSTB}	Input clock stability (measured between adjacent clocks)		50	ps			

Notes to Table 15:

- (1) The PLL input frequency range for the EP20K100-1X device for 1x multiplication is 25 MHz to 175 MHz.
- (2) All input clock specifications must be met. The PLL may not lock onto an incoming clock if the clock specifications are not met, creating an erroneous clock within the device.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured first. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration, because the lock time is less than the configuration time.
- (4) The jitter specification is measured under long-term observation.
- (5) If the input clock stability is 100 ps, t_{JITTER} is 250 ps.

Table 16 summarizes the APEX 20K ClockLock and ClockBoost parameters for -2 speed grade devices.

Symbol	Parameter	Min	Max	Unit
f _{OUT}	Output frequency	25	170	MHz
f _{CLK1}	Input clock frequency (ClockBoost clock multiplication factor equals 1)	25	170	MHz
f _{CLK2}	Input clock frequency (ClockBoost clock multiplication factor equals 2)	16	80	MHz
f _{CLK4}	Input clock frequency (ClockBoost clock multiplication factor equals 4)	10	34	MHz
t _{OUTDUTY}	Duty cycle for ClockLock/ClockBoost-generated clock	40	60	%
f _{CLKDEV}	Input deviation from user specification in the Quartus II software (ClockBoost clock multiplication factor equals one) (1)		25,000 (2)	PPM
t _R	Input rise time		5	ns
t _F	Input fall time		5	ns
t _{LOCK}	Time required for ClockLock/ ClockBoost to acquire lock (3)		10	μѕ
t _{SKEW}	Skew delay between related ClockLock/ ClockBoost-generated clock	500	500	ps
t _{JITTER}	Jitter on ClockLock/ ClockBoost-generated clock (4)		200	ps
t _{INCLKSTB}	Input clock stability (measured between adjacent clocks)		50	ps

Combal Bayanatay Canditions Min May He									
Symbol	Parameter	Conditions	Min	Max	Unit				
V _{CCINT}	Supply voltage for internal logic and input buffers	(4), (5)	2.375 (2.375)	2.625 (2.625)	V				
V _{CCIO} Supply voltage for output but 3.3-V operation	Supply voltage for output buffers, 3.3-V operation	(4), (5)	3.00 (3.00)	3.60 (3.60)	٧				
	Supply voltage for output buffers, 2.5-V operation	(4), (5)	2.375 (2.375)	2.625 (2.625)	V				
V _I	Input voltage	(3), (6)	-0.5	5.75	V				
Vo	Output voltage		0	V _{CCIO}	V				
T _J	Junction temperature	For commercial use	0	85	°C				
		For industrial use	-40	100	°C				
t _R	Input rise time			40	ns				
t _F	Input fall time			40	ns				

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{IH}	High-level input voltage		1.7, 0.5 × V _{CCIO} (9)		5.75	٧
V _{IL}	Low-level input voltage		-0.5		0.8, 0.3 × V _{CCIO} (9)	V
V _{OH}	3.3-V high-level TTL output voltage	I _{OH} = -8 mA DC, V _{CCIO} = 3.00 V (10)	2.4			٧
	3.3-V high-level CMOS output voltage	I _{OH} = -0.1 mA DC, V _{CCIO} = 3.00 V (10)	V _{CCIO} - 0.2			V
-	3.3-V high-level PCI output voltage	$I_{OH} = -0.5 \text{ mA DC},$ $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (10)	0.9 × V _{CCIO}			V
	2.5-V high-level output voltage	I _{OH} = -0.1 mA DC, V _{CCIO} = 2.30 V (10)	2.1			٧
		I _{OH} = -1 mA DC, V _{CCIO} = 2.30 V (10)	2.0			V
		I _{OH} = -2 mA DC, V _{CCIO} = 2.30 V (10)	1.7			٧

Table 2	Table 26. APEX 20K 5.0-V Tolerant Device CapacitanceNotes (2), (14)								
Symbol	Parameter	Conditions	Min	Max	Unit				
C _{IN}	Input capacitance	V _{IN} = 0 V, f = 1.0 MHz		8	pF				
C _{INCLK}	Input capacitance on dedicated clock pin	V _{IN} = 0 V, f = 1.0 MHz		12	pF				
C _{OUT}	Output capacitance	V _{OUT} = 0 V, f = 1.0 MHz		8	pF				

Notes to Tables 23 through 26:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) All APEX 20K devices are 5.0-V tolerant.
- (3) Minimum DC input is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 5.75 V for input currents less than 100 mA and periods shorter than 20 ns.
- (4) Numbers in parentheses are for industrial-temperature-range devices.
- (5) Maximum V_{CC} rise time is 100 ms, and V_{CC} must rise monotonically.
- (6) All pins, including dedicated inputs, clock I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- (7) Typical values are for $T_A = 25^{\circ}$ C, $V_{CCINT} = 2.5$ V, and $V_{CCIO} = 2.5$ or 3.3 V.
- (8) These values are specified in the APEX 20K device recommended operating conditions, shown in Table 26 on page 62.
- (9) The APEX 20K input buffers are compatible with 2.5-V and 3.3-V (LVTTL and LVCMOS) signals. Additionally, the input buffers are 3.3-V PCI compliant when V_{CCIO} and V_{CCINT} meet the relationship shown in Figure 33 on page 68.
- (10) The I_{OH} parameter refers to high-level TTL, PCI or CMOS output current.
- (11) The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
- (12) This value is specified for normal device operation. The value may vary during power-up.
- (13) Pin pull-up resistance values will be lower if an external source drives the pin higher than V_{CCIO} .
- (14) Capacitance is sample-tested only.

Tables 27 through 30 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for 1.8-V APEX 20KE devices.

Table 27. APEX 20KE Device Absolute Maximum Ratings Note (1)								
Symbol	Parameter	Conditions	Min	Max	Unit			
V_{CCINT}	Supply voltage	With respect to ground (2)	-0.5	2.5	V			
V_{CCIO}			-0.5	4.6	V			
V _I	DC input voltage		-0.5	4.6	V			
I _{OUT}	DC output current, per pin		-25	25	mA			
T _{STG}	Storage temperature	No bias	-65	150	°C			
T _{AMB}	Ambient temperature	Under bias	-65	135	°C			
TJ	Junction temperature	PQFP, RQFP, TQFP, and BGA packages, under bias		135	° C			
		Ceramic PGA packages, under bias		150	°C			



For DC Operating Specifications on APEX 20KE I/O standards, please refer to *Application Note 117 (Using Selectable I/O Standards in Altera Devices).*

Table 30. APEX 20KE Device Capacitance Note (15)								
Symbol	Parameter	Conditions	Unit					
C _{IN}	Input capacitance	V _{IN} = 0 V, f = 1.0 MHz		8	pF			
C _{INCLK}	Input capacitance on dedicated clock pin	V _{IN} = 0 V, f = 1.0 MHz		12	pF			
C _{OUT}	Output capacitance	V _{OUT} = 0 V, f = 1.0 MHz		8	pF			

Notes to Tables 27 through 30:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 5.75 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) Maximum V_{CC} rise time is 100 ms, and V_{CC} must rise monotonically.
- (5) Minimum DC input is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to the voltage shown in the following table based on input duty cycle for input currents less than 100 mA. The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to 100% duty cycle.

Vin Max. Duty Cycle 4.0V 100% (DC) 4.1 90% 4.2 50% 4.3 30% 4.4 17% 4.5 10%

- (6) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- Typical values are for $T_A = 25^{\circ}$ C, $V_{CCINT} = 1.8$ V, and $V_{CCIO} = 1.8$ V, 2.5 V or 3.3 V.
- (8) These values are specified under the APEX 20KE device recommended operating conditions, shown in Table 24 on page 60.
- (9) Refer to Application Note 117 (Using Selectable I/O Standards in Altera Devices) for the V_{IH}, V_{IL}, V_{OH}, V_{OL}, and I_I parameters when VCCIO = 1.8 V.
- (10) The APEX 20KE input buffers are compatible with 1.8-V, 2.5-V and 3.3-V (LVTTL and LVCMOS) signals. Additionally, the input buffers are 3.3-V PCI compliant. Input buffers also meet specifications for GTL+, CTT, AGP, SSTL-2, SSTL-3, and HSTL.
- (11) The I_{OH} parameter refers to high-level TTL, PCI, or CMOS output current.
- (12) The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
- (13) This value is specified for normal device operation. The value may vary during power-up.
- (14) Pin pull-up resistance values will be lower if an external source drives the pin higher than V_{CCIO}.
- (15) Capacitance is sample-tested only.

Figure 33 shows the relationship between V_{CCIO} and V_{CCINT} for 3.3-V PCI compliance on APEX 20K devices.

Table 62. EP20K	I GOL IMAX LOL	, iming mid	1		T		Unit
Symbol	-	1		-2	-:	-3	
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.61		1.84		1.97	ns
t _{ESBSRC}		2.57		2.97		3.20	ns
t _{ESBAWC}		0.52		4.09		4.39	ns
t _{ESBSWC}		3.17		3.78		4.09	ns
t _{ESBWASU}	0.56		6.41		0.63		ns
t _{ESBWAH}	0.48		0.54		0.55		ns
t _{ESBWDSU}	0.71		0.80		0.81		ns
t _{ESBWDH}	.048		0.54		0.55		ns
t _{ESBRASU}	1.57		1.75		1.87		ns
t _{ESBRAH}	0.00		0.00		0.20		ns
t _{ESBWESU}	1.54		1.72		1.80		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.16		-0.20		-0.20		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.12		0.08		0.13		ns
t _{ESBRADDRSU}	0.17		0.15		0.19		ns
t _{ESBDATACO1}		1.20		1.39		1.52	ns
t _{ESBDATACO2}		2.54		2.99		3.22	ns
t _{ESBDD}		3.06		3.56		3.85	ns
t _{PD}		1.73		2.02		2.20	ns
t _{PTERMSU}	1.11		1.26		1.38		ns
t _{PTERMCO}		1.19		1.40		1.08	ns

Table 63. EP20K100E f _{MAX} Routing Delays										
Symbol	-1		-2		-3		Unit			
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.24		0.27		0.29	ns			
t _{F5-20}		1.04		1.26		1.52	ns			
t _{F20+}		1.12		1.36		1.86	ns			

Symbol	-	1	-	2	-;	3	Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.65		2.02		2.11	ns
t _{ESBSRC}		2.21		2.70		3.11	ns
t _{ESBAWC}		3.04		3.79		4.42	ns
t _{ESBSWC}		2.81		3.56		4.10	ns
t _{ESBWASU}	0.54		0.66		0.73		ns
t _{ESBWAH}	0.36		0.45		0.47		ns
t _{ESBWDSU}	0.68		0.81		0.94		ns
t _{ESBWDH}	0.36		0.45		0.47		ns
t _{ESBRASU}	1.58		1.87		2.06		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.41		1.71		2.00		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.02		-0.03		0.09		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.14		0.17		0.35		ns
t _{ESBRADDRSU}	0.21		0.27		0.43		ns
t _{ESBDATACO1}		1.04		1.30		1.46	ns
t _{ESBDATACO2}		2.15		2.70		3.16	ns
t _{ESBDD}		2.69		3.35		3.97	ns
t _{PD}		1.55		1.93	_	2.29	ns
t _{PTERMSU}	1.01		1.23		1.52		ns
t _{PTERMCO}		1.06		1.32		1.04	ns

Table 69. EP20K160E f _{MAX} Routing Delays										
Symbol	-	1		-2	-3		Unit			
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.25		0.26		0.28	ns			
t _{F5-20}		1.00		1.18		1.35	ns			
t _{F20+}		1.95		2.19		2.30	ns			

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.34		1.43		1.55		ns
t _{CL}	1.34		1.43		1.55		ns
t _{CLRP}	0.18		0.19		0.21		ns
t _{PREP}	0.18		0.19		0.21		ns
t _{ESBCH}	1.34		1.43		1.55		ns
t _{ESBCL}	1.34		1.43		1.55		ns
t _{ESBWP}	1.15		1.45		1.73		ns
t _{ESBRP}	0.93		1.15		1.38		ns

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.23		2.34		2.47		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	5.07	2.00	5.59	2.00	6.13	ns
t _{INSUPLL}	2.12		2.07		=		ns
t _{INHPLL}	0.00		0.00		=		ns
toutcople	0.50	3.00	0.50	3.35	-	-	ns

Symbol	-1		-2		-3		Unit	
	Min	Max	Min	Max	Min	Max		
t _{ESBARC}		1.79		2.44		3.25	ns	
t _{ESBSRC}		2.40		3.12		4.01	ns	
t _{ESBAWC}		3.41		4.65		6.20	ns	
t _{ESBSWC}		3.68		4.68		5.93	ns	
t _{ESBWASU}	1.55		2.12		2.83		ns	
t _{ESBWAH}	0.00		0.00		0.00		ns	
t _{ESBWDSU}	1.71		2.33		3.11		ns	
t _{ESBWDH}	0.00		0.00		0.00		ns	
t _{ESBRASU}	1.72		2.34		3.13		ns	
t _{ESBRAH}	0.00		0.00		0.00		ns	
t _{ESBWESU}	1.63		2.36		3.28		ns	
t _{ESBWEH}	0.00		0.00		0.00		ns	
t _{ESBDATASU}	0.07		0.39		0.80		ns	
t _{ESBDATAH}	0.13		0.13		0.13		ns	
t _{ESBWADDRSU}	0.27		0.67		1.17		ns	
t _{ESBRADDRSU}	0.34		0.75		1.28		ns	
t _{ESBDATACO1}		1.03		1.20		1.40	ns	
t _{ESBDATACO2}		2.33		3.18		4.24	ns	
t _{ESBDD}		3.41		4.65		6.20	ns	
t _{PD}		1.68		2.29		3.06	ns	
t _{PTERMSU}	0.96		1.48		2.14		ns	
t _{PTERMCO}		1.05		1.22		1.42	ns	

Table 81. EP20K300E f _{MAX} Routing Delays										
Symbol	-	1		2	-	Unit				
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.22		0.24		0.26	ns			
t _{F5-20}		1.33		1.43		1.58	ns			
t _{F20+}		3.63		3.93		4.35	ns			

Tables 85 through 90 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K400E APEX 20KE devices.

Table 85. EP20K400E f _{MAX} LE Timing Microparameters										
Symbol	-1 Spee	d Grade	-2 Spec	ed Grade	-3 Speed Grade		Unit			
	Min	Max	Min	Max	Min	Max	7			
t _{SU}	0.23		0.23		0.23		ns			
t _H	0.23		0.23		0.23		ns			
t _{CO}		0.25		0.29		0.32	ns			
t _{LUT}		0.70		0.83		1.01	ns			

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit	
	Min	Max	Min	Max	Min	Max		
t _{ESBARC}		1.78		2.02		1.95	ns	
t _{ESBSRC}		2.52		2.91		3.14	ns	
t _{ESBAWC}		3.52		4.11		4.40	ns	
t _{ESBSWC}		3.23		3.84		4.16	ns	
t _{ESBWASU}	0.62		0.67		0.61		ns	
t _{ESBWAH}	0.41		0.55		0.55		ns	
t _{ESBWDSU}	0.77		0.79		0.81		ns	
t _{ESBWDH}	0.41		0.55		0.55		ns	
t _{ESBRASU}	1.74		1.92		1.85		ns	
t _{ESBRAH}	0.00		0.01		0.23		ns	
t _{ESBWESU}	2.07		2.28		2.41		ns	
t _{ESBWEH}	0.00		0.00		0.00		ns	
t _{ESBDATASU}	0.25		0.27		0.29		ns	
t _{ESBDATAH}	0.13		0.13		0.13		ns	
t _{ESBWADDRSU}	0.11		0.04		0.11		ns	
t _{ESBRADDRSU}	0.14		0.11		0.16		ns	
t _{ESBDATACO1}		1.29		1.50		1.63	ns	
t _{ESBDATACO2}		2.55		2.99		3.22	ns	
t _{ESBDD}		3.12		3.57		3.85	ns	
t _{PD}		1.84		2.13		2.32	ns	
t _{PTERMSU}	1.08		1.19		1.32	_	ns	
t _{PTERMCO}		1.31		1.53		1.66	ns	

Table 105. EP20K1500E f _{MAX} Routing Delays										
Symbol	-1 Spee	d Grade	-2 Spe	ed Grade	-3 Speed Grade		Unit			
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.28		0.28		0.28	ns			
t _{F5-20}		1.36		1.50		1.62	ns			
t _{F20+}		4.43		4.48		5.07	ns			